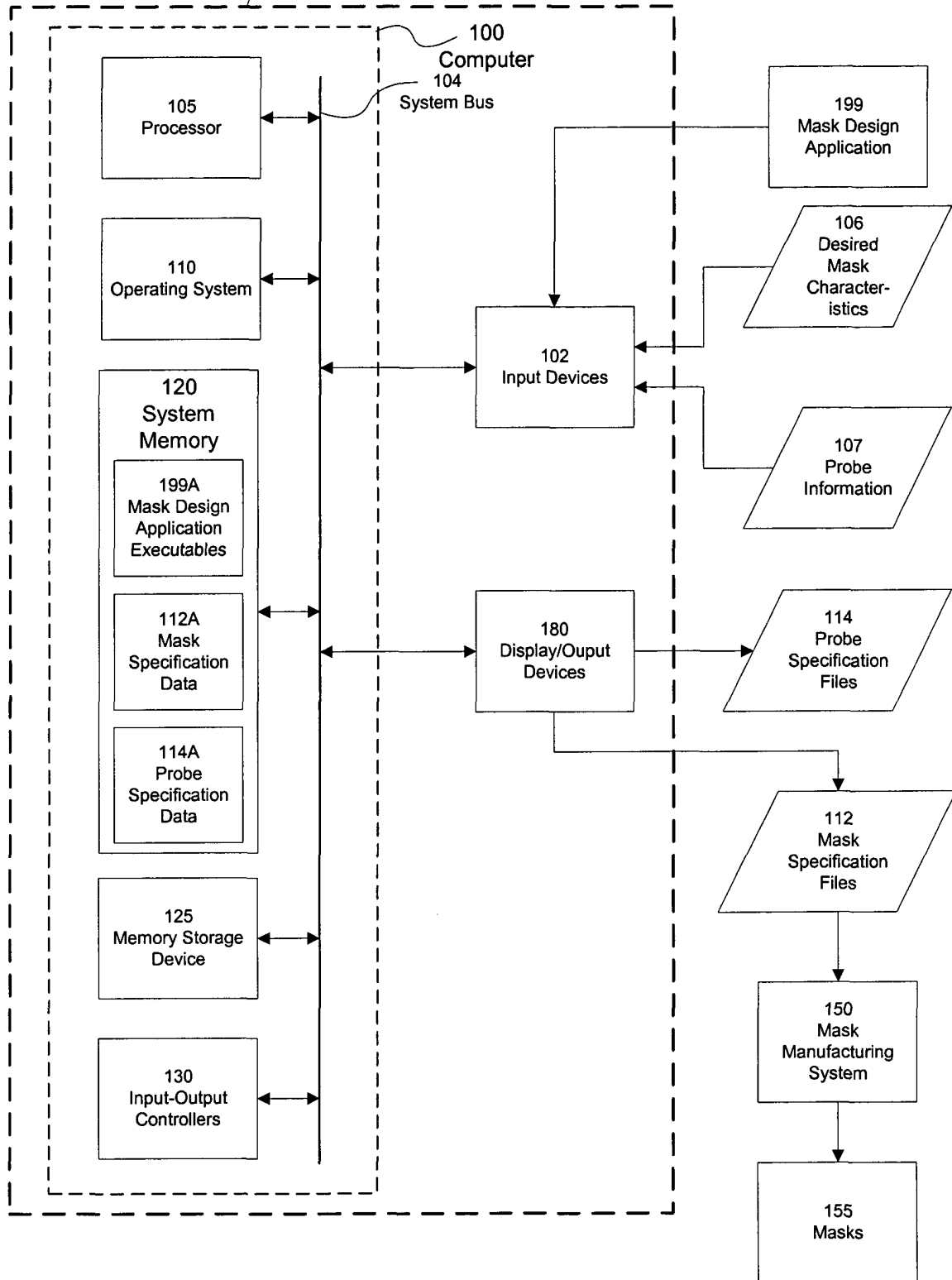


# Mask Design System

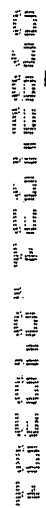
FIGURE 1



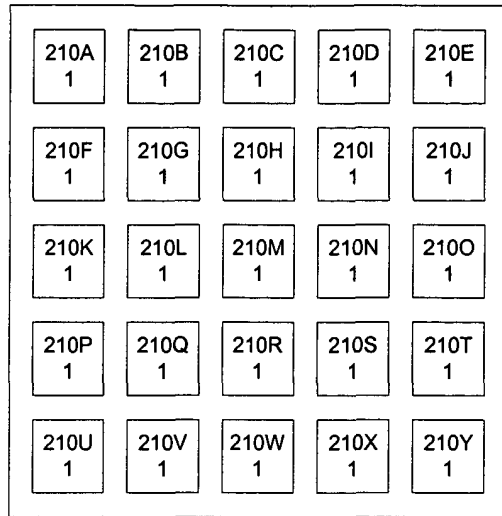
24



**FIGURE 2B**  
**(PRIOR ART)**



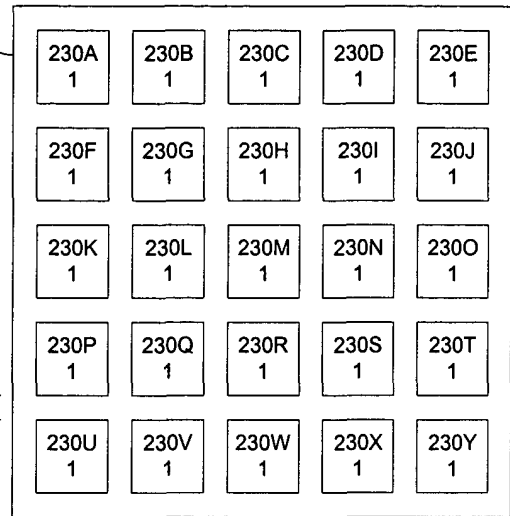
**FIGURE 2C**



155A-1  
Mask

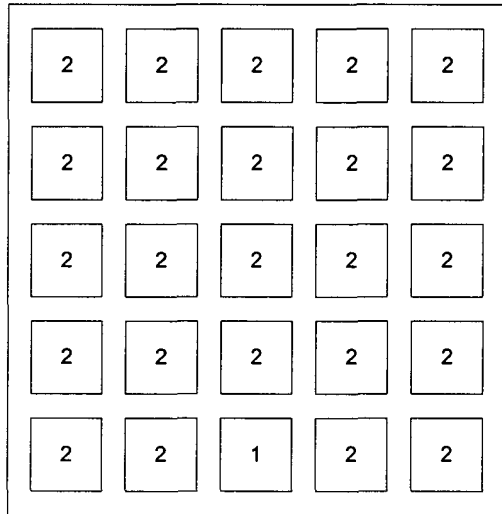
240  
Wafer

**FIGURE 2D**



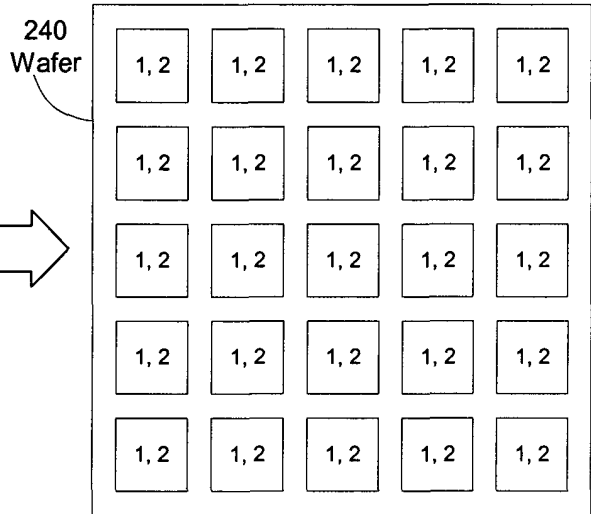
212  
Dicing Offset  
e.g., 3 mm

**FIGURE 2G**



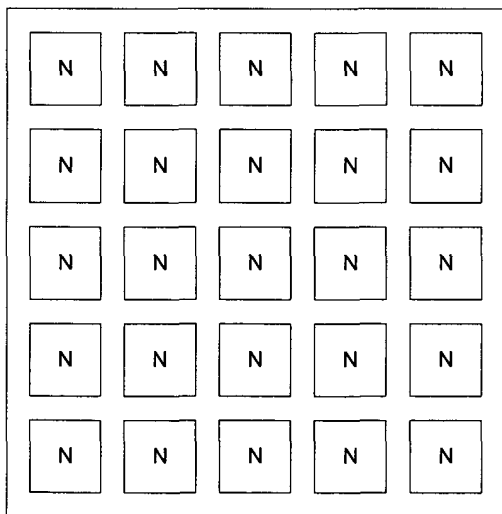
155A-2  
Mask

**FIGURE 2H**

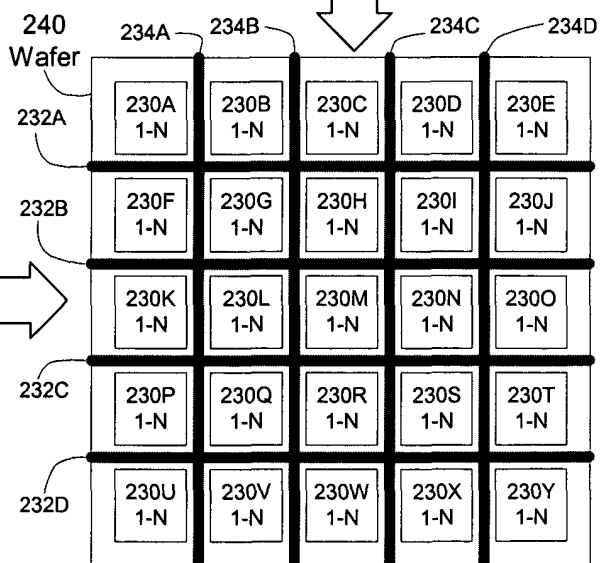


240  
Wafer

**FIGURE 2E**



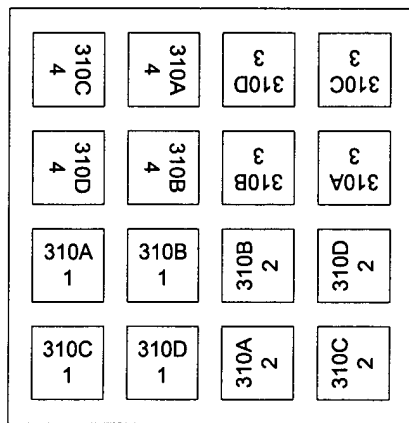
155A-N  
Mask



240  
Wafer

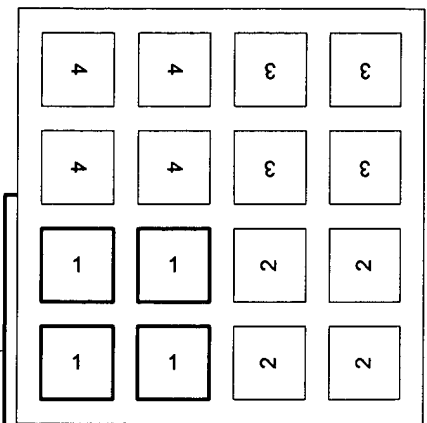
**FIGURE 2F (PRIOR ART)**

**FIGURE 3A**



155B Mask  
340 Wafer

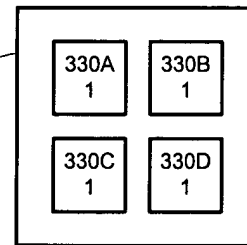
**FIGURE 3B**



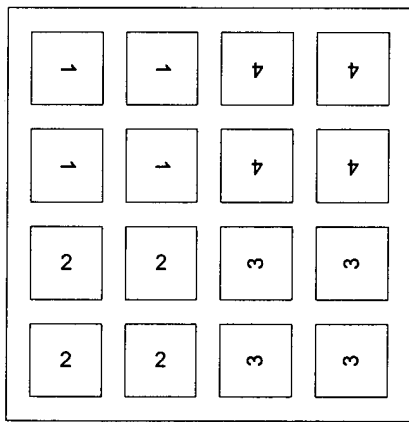
340 Wafer

**FIGURE 3C**

340 Wafer

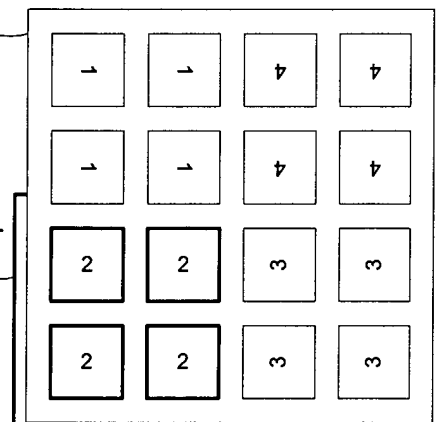


**FIGURE 3C**



155B Mask  
340 Wafer

**FIGURE 3D**

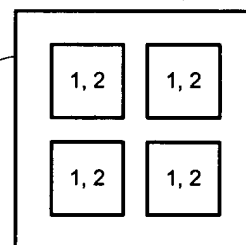


155B Mask  
340 Wafer

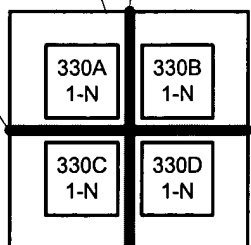
312  
Dicing Offset  
e.g., 3 mm

**FIGURE 3E**

340 Wafer

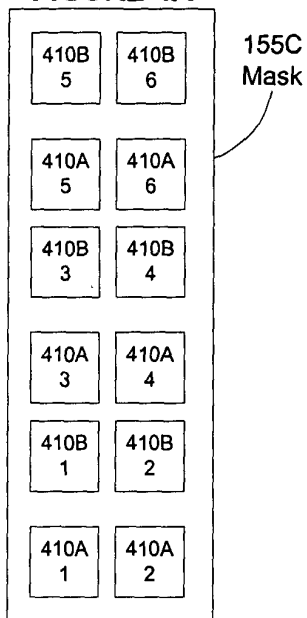


**FIGURE 3F**

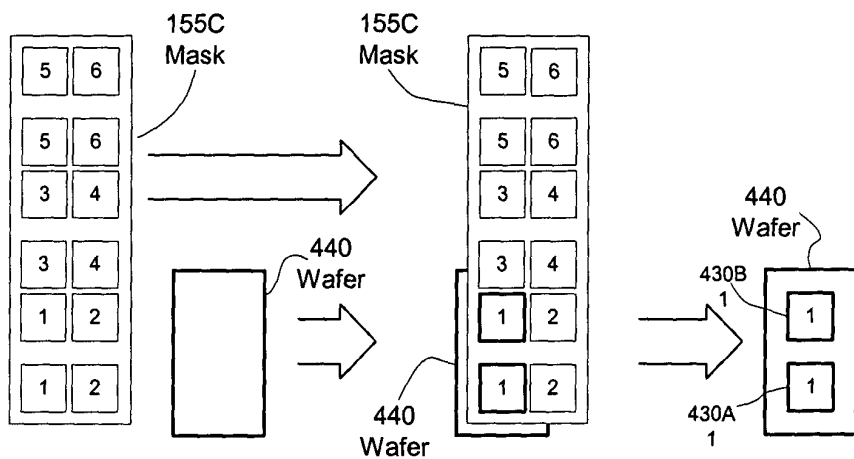


340 Wafer  
332  
334

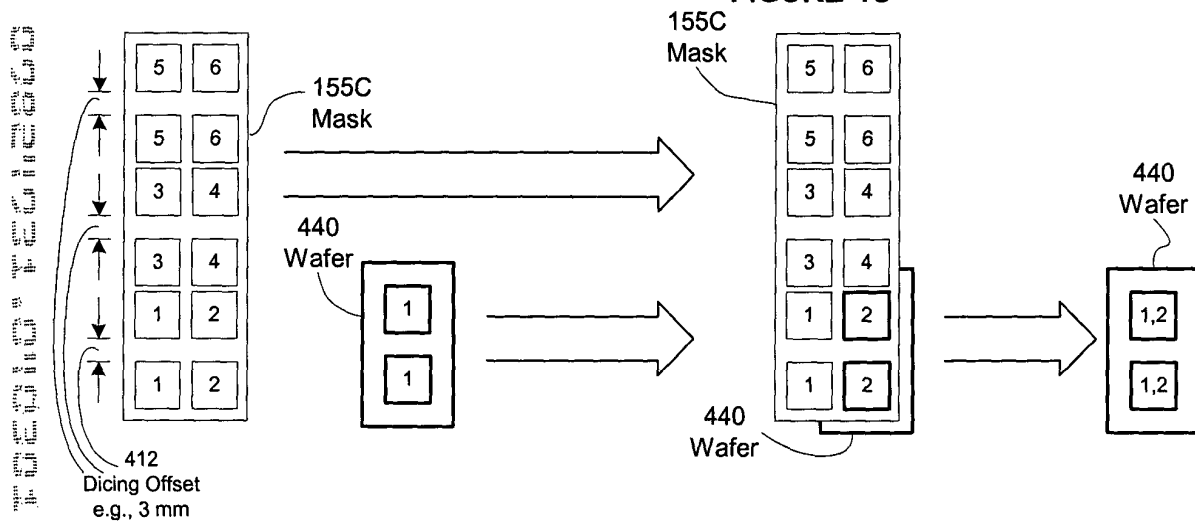
**FIGURE 4A**



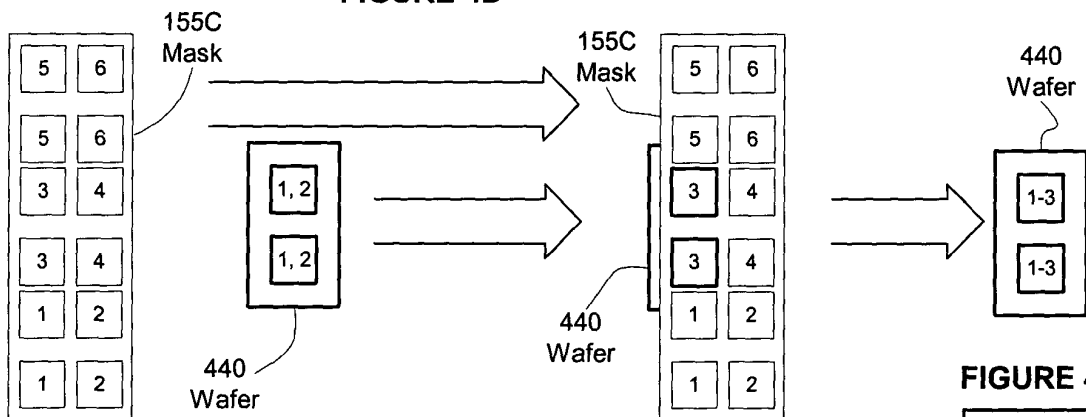
**FIGURE 4B**



**FIGURE 4C**



**FIGURE 4D**



**FIGURE 4E**

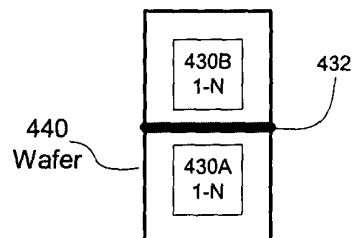


FIGURE 5A

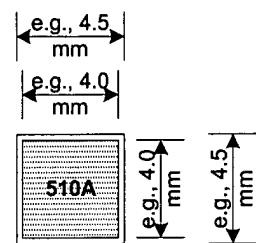


FIGURE 5B

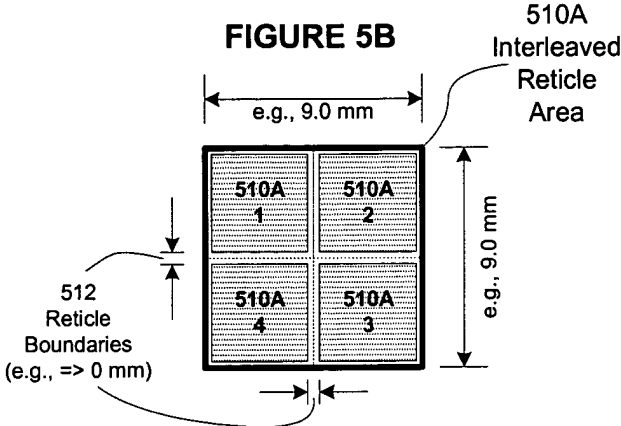


FIGURE 5C

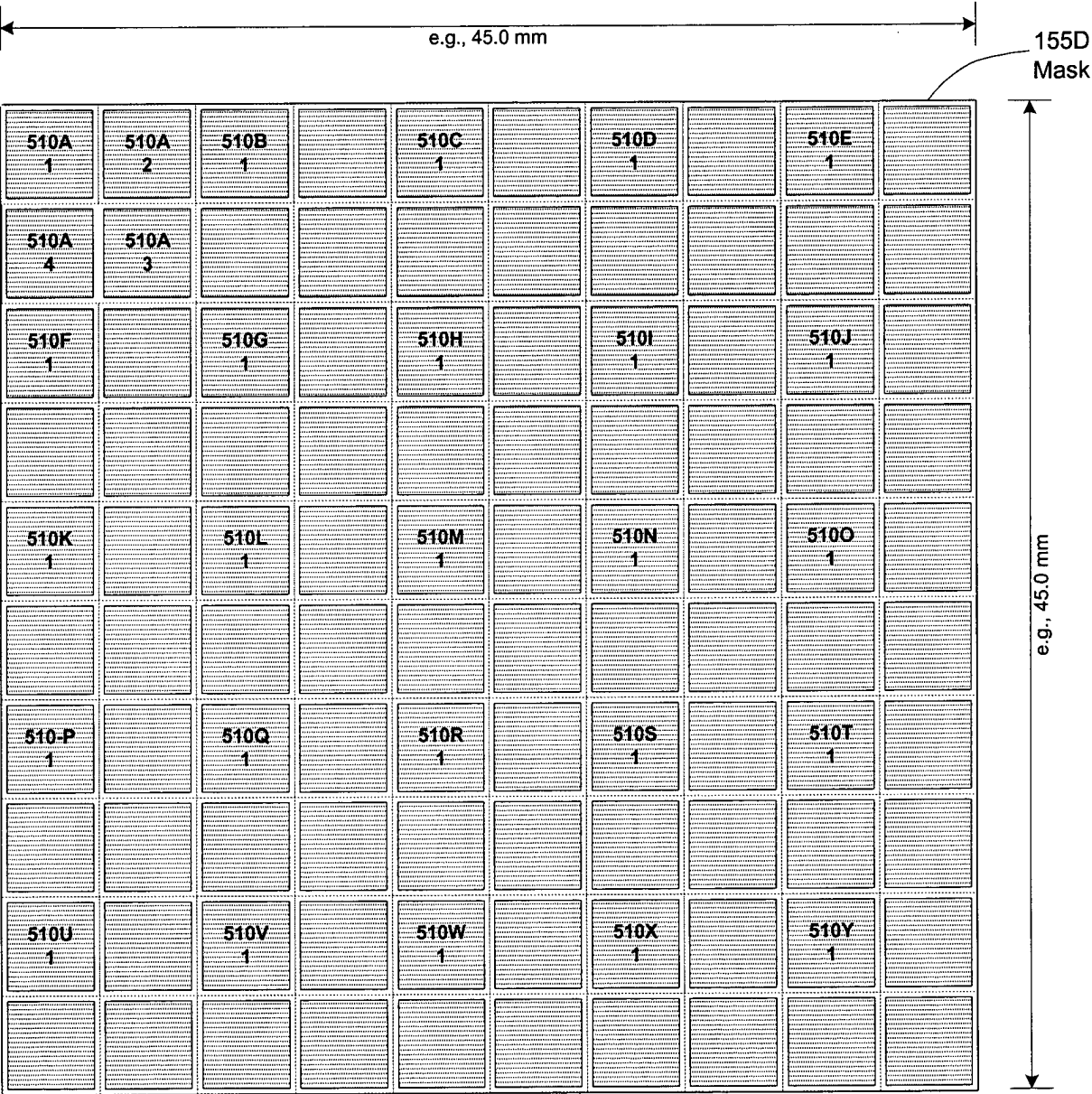


FIGURE 6A

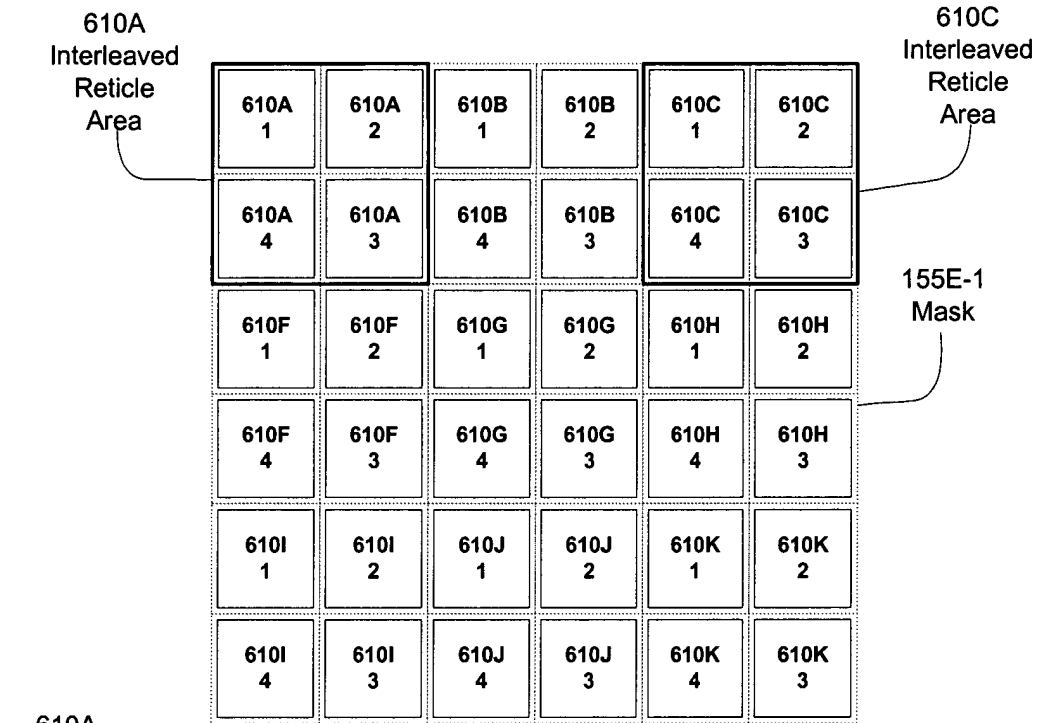


FIGURE 6B

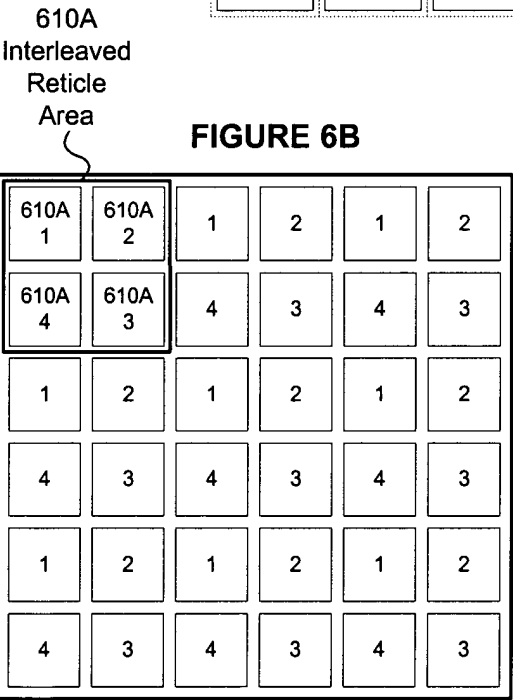


FIGURE 6C

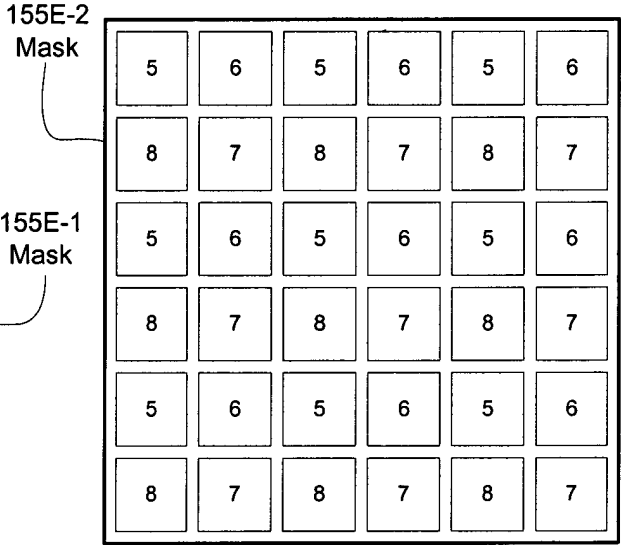


FIGURE 6D - STEP 1

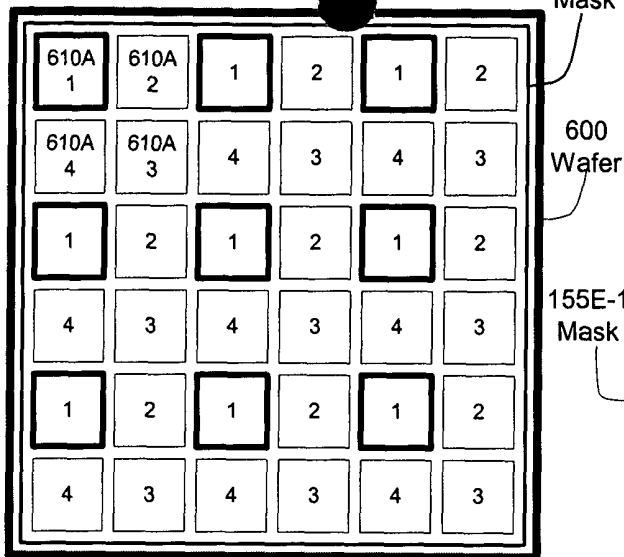


FIGURE 6E - STEP 2

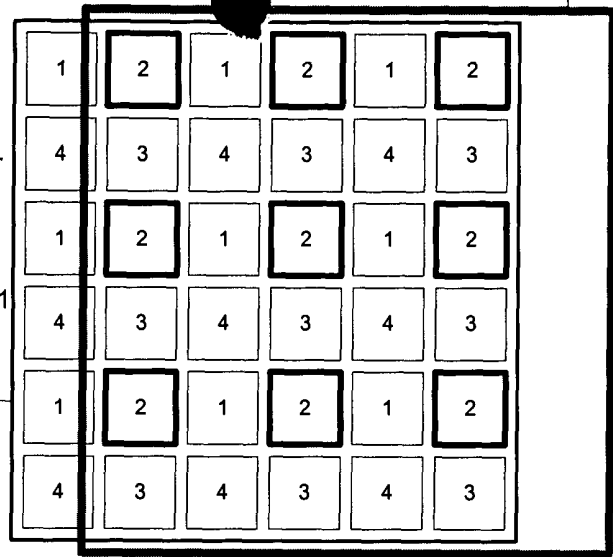


FIGURE 6F - STEP 3

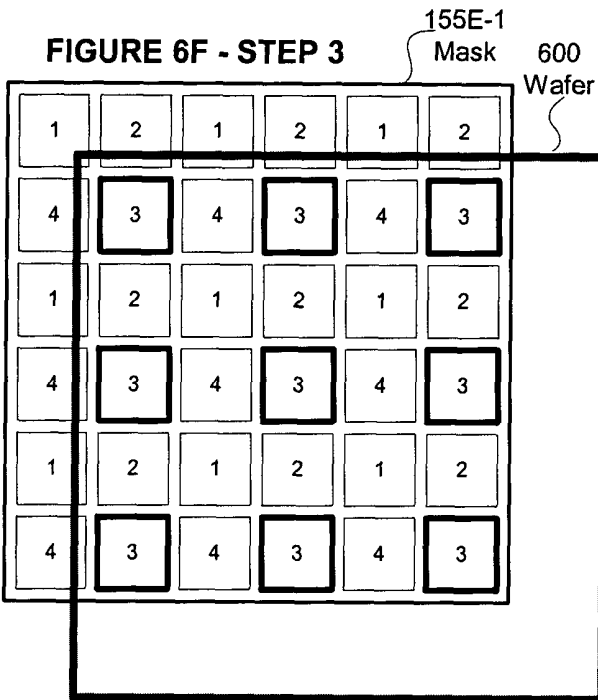


FIGURE 6G - STEP 4

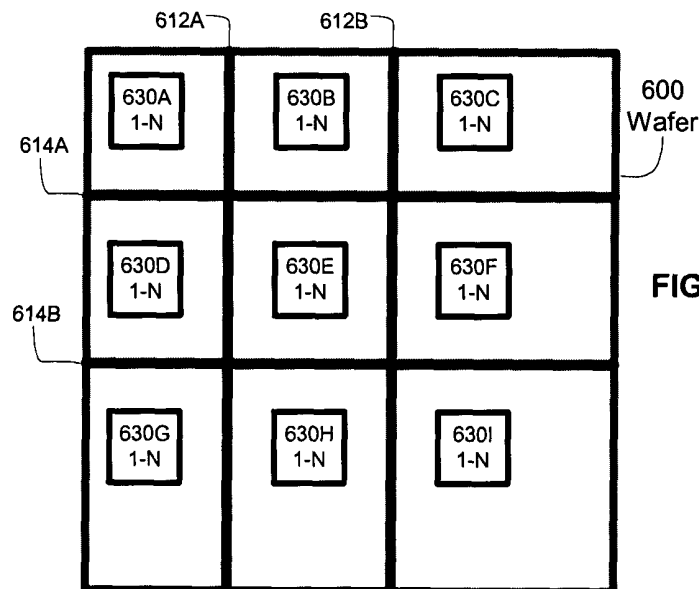
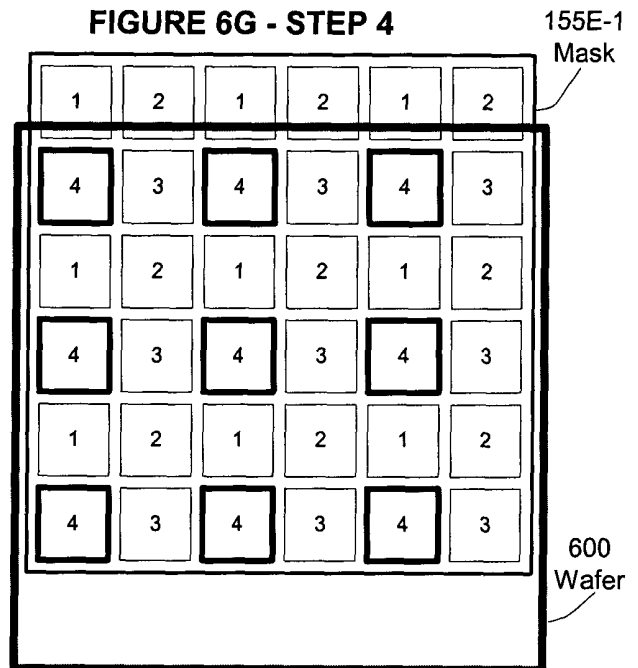
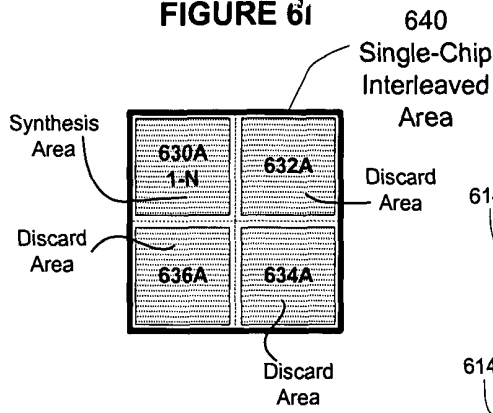


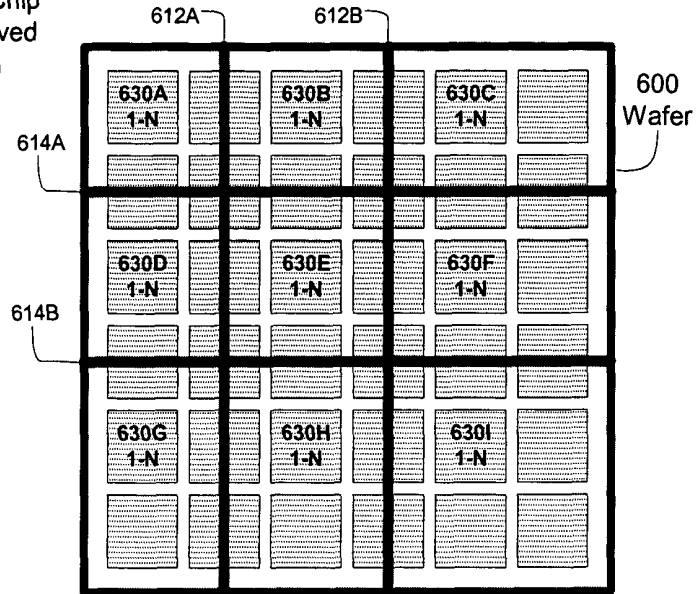
FIGURE 6H



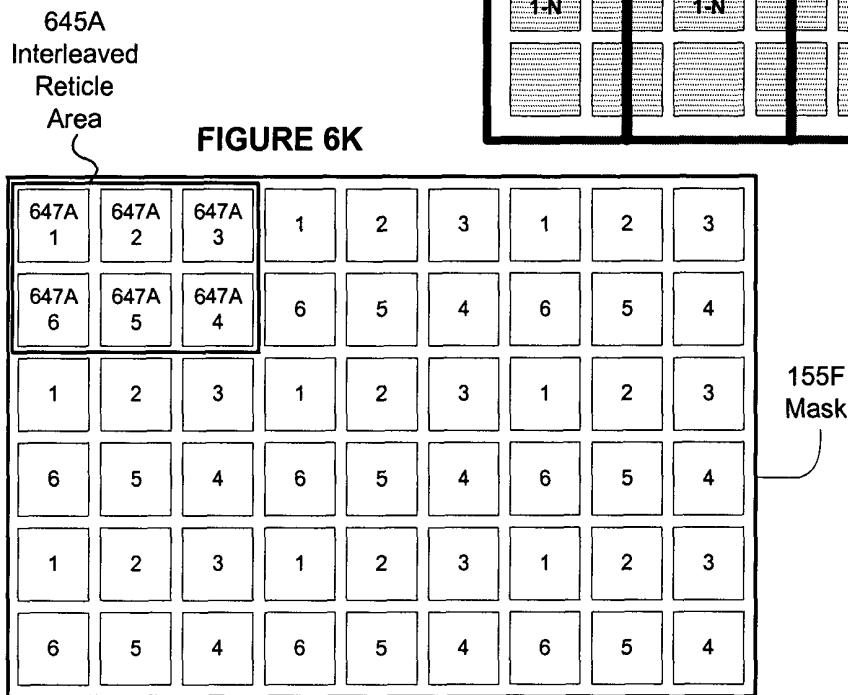
**FIGURE 6I**



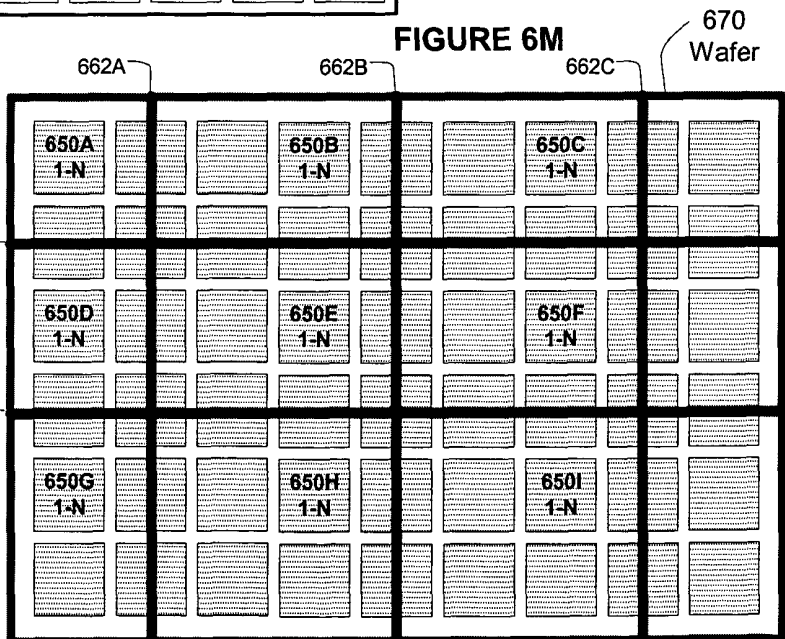
**FIGURE 6J**



**FIGURE 6K**



**FIGURE 6M**



**FIGURE 6L**

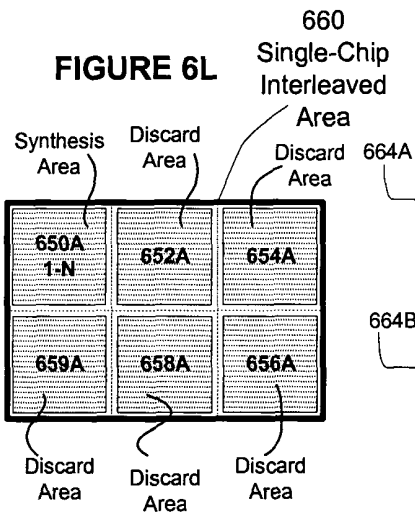


FIGURE 7

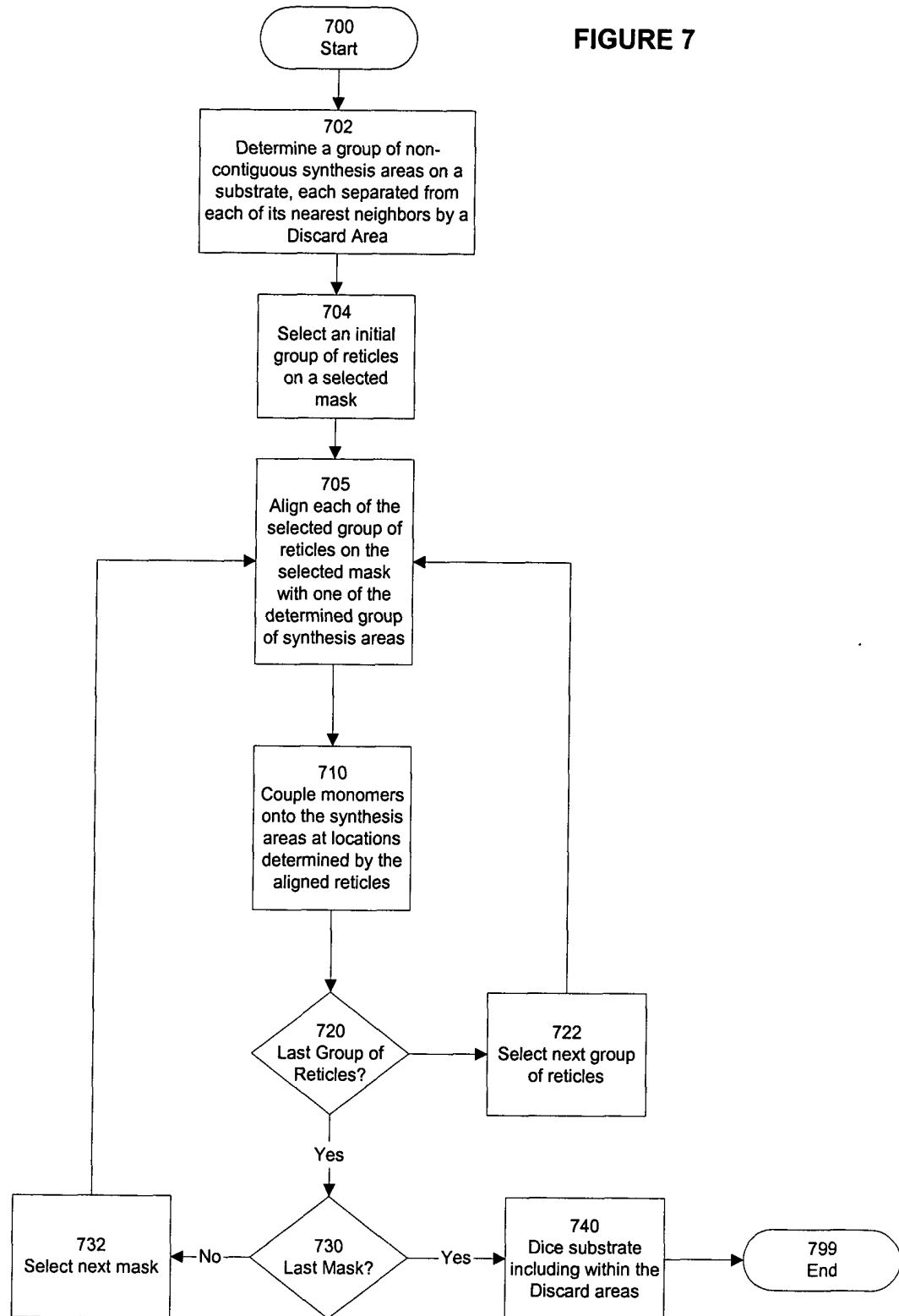


FIGURE 8

